

# Characterization and Development of Advanced Heat Transfer Technologies

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**Project Duration: FY08 to FY10**

**DOE FreedomCAR and Vehicle Technologies Program  
Advanced Power Electronics and  
Electric Machines Projects  
FY08 Kickoff Meeting**

**National Transportation Research Center  
Knoxville, Tennessee**

**November 8, 2007**



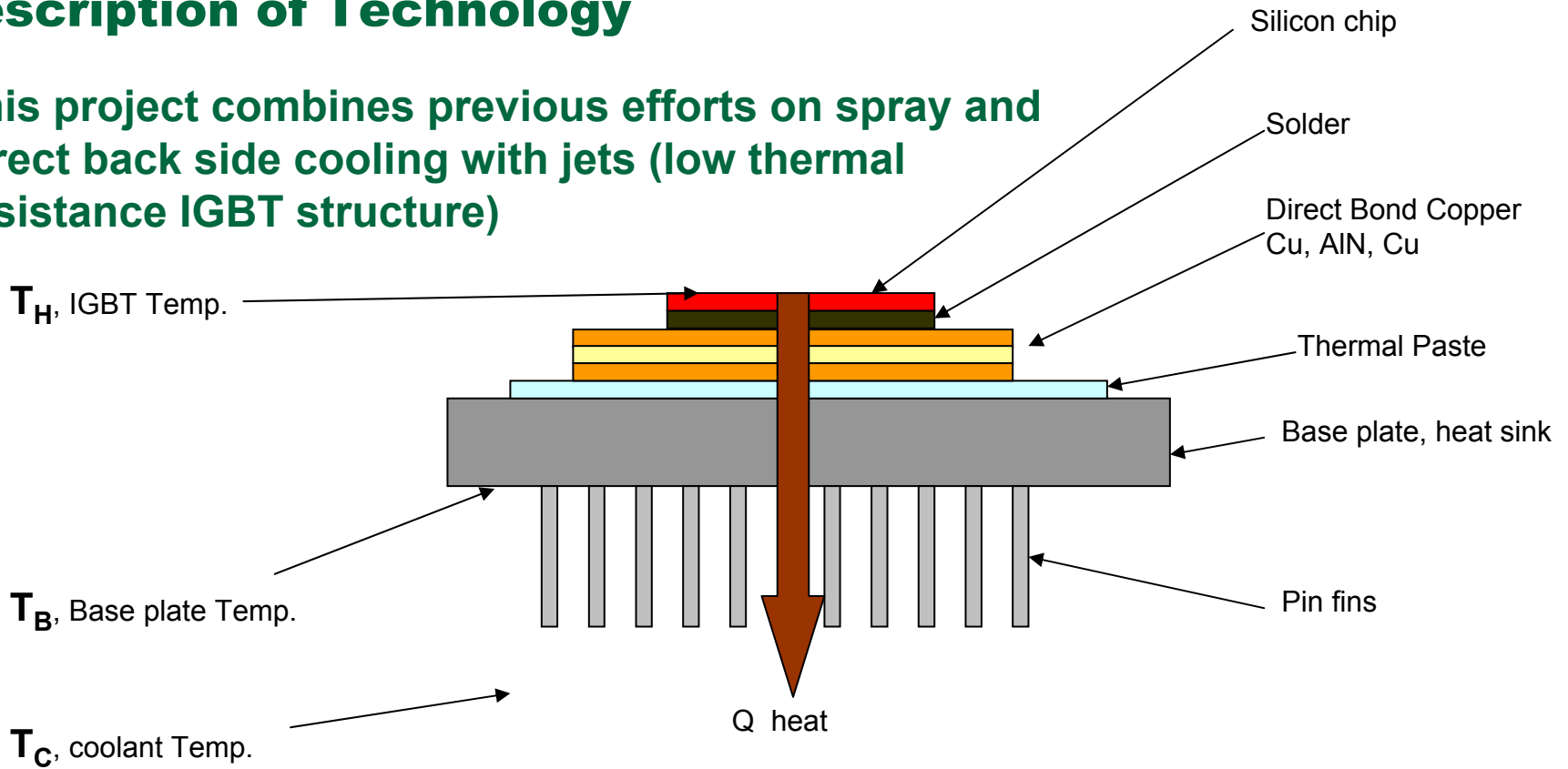
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# The Problem

- Enable the use of 105°C coolant to reduce the thermal control cost by completely eliminating a separate coolant loop.
- For performance and long term reliability, die temperature needs to be below 125° C with conventional IGBT technology (150° – 175° C with Trench IGBT).
- Current approach of using a separate coolant loop at 70° C is costly relative to the overall FreedomCAR goals [for 2020 cost target of \$8/kW for a 55 kW traction system].
- Target for specific power at peak load is > 1.2 kW/kg while for volumetric power density is > 3.5 kW/liter.

# Description of Technology

This project combines previous efforts on spray and direct back side cooling with jets (low thermal resistance IGBT structure)



$$Q = h A (T_B - T_C)$$

$$Q = \frac{(T_H - T_B)}{R_{solder} + R_{DBC} + R_{TIM} + R_B}$$

# Description of Technology

Improve PE device efficiency (ORNL)

Optimize base plate temperature

- PE materials development (working closely with ORNL)
- Reduce thermal resistance

coolant temperature is 105° C

$$Q = h A (T_B - T_C)$$

Increase surface area

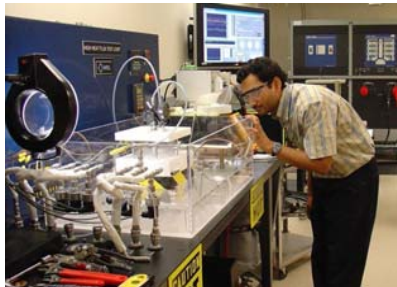
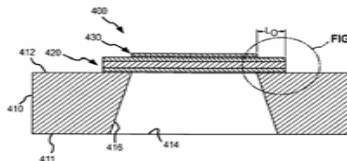
- Fin shape optimization
- Double sided cooling
- Surface enhancements
- Thermal Spreading



Enhance heat transfer coefficient

- jet/spray cooling
- self-oscillating jets
- phase change

U.S. Patent Mar. 13, 2007 Sheet 4 of 11 US 7,190,581 B1



# Uniqueness of Project and Impacts

- **New approach looks at novel thermal solutions which are integrated with Power Electronics (PE) development by closely working with ORNL PE Tech and industry partners.**
- **By looking at thermal aspects during PE development, innovative PE could be explored, which have not thought to be practical.**
- **Efficient thermal control would aid in making PE devices smaller which could drive down the cost.**

# Accomplishments to Date (for projects funded in prior FYs)

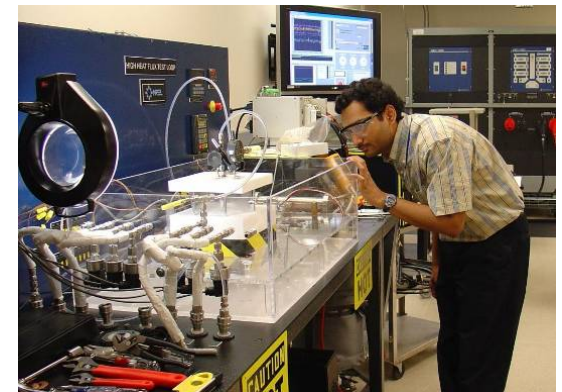
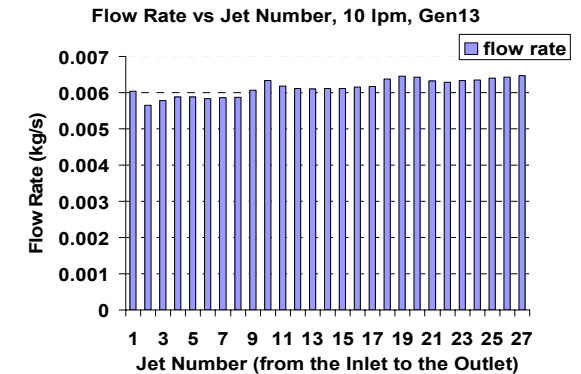
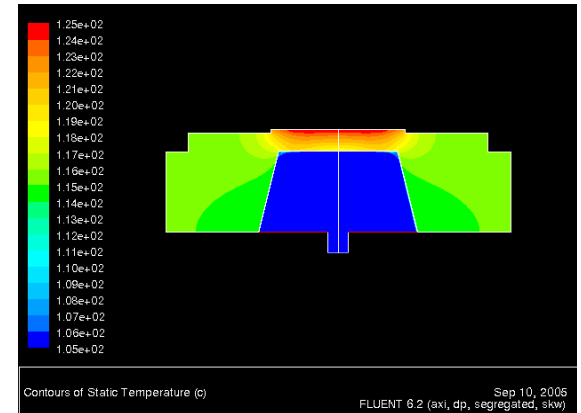
## Low Thermal Resistance Power Module and Oscillating Jets

### Status

- Awarded patent for “Low Thermal Resistance Power Module Assembly”
- Completed testing to show the potential of self-oscillating jets for power electronics cooling

### Benefits

- Concept enhances heat transfer from power electronic components by allowing forced liquid jets to cool the backside of the electronics
- By transferring heat more effectively than existing methods, the weight and cost of power electronics devices can be drastically reduced
- The velocity variation between the jets is within 8%
- Self-oscillating jets have the potential of further improving heat transfer (about 18%) with no moving parts



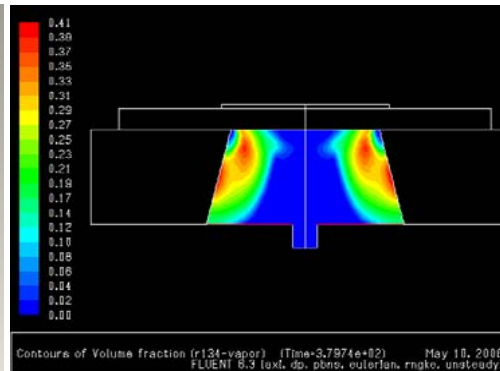
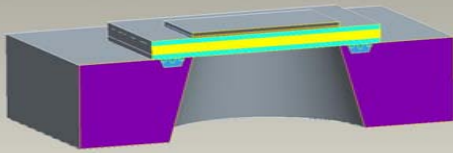
# Accomplishments to Date (for projects funded in prior FYs)

## Two-phase Modeling, NREL

### Status

- Two phase modeling results published in International Journal of Heat and Mass Transfer
- Validation of NREL modeling with experimental data available in the literature
- Demonstrated conditions for two-phase with R134a that would dissipate 200 W/cm<sup>2</sup> while keeping the die temperature close to 125° C

### Simulations with R134a jet



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International Journal of **HEAT and MASS TRANSFER**

[www.elsevier.com/locate/ijhmt](http://www.elsevier.com/locate/ijhmt)

Numerical simulations of nucleate boiling in impinging jets: Applications in power electronics cooling <sup>☆</sup>

Sreekant Narumanchi <sup>a,\*</sup>, Andrey Troshko <sup>b</sup>, Desikan Bharathan <sup>a</sup>, Vahab Hassani <sup>a</sup>

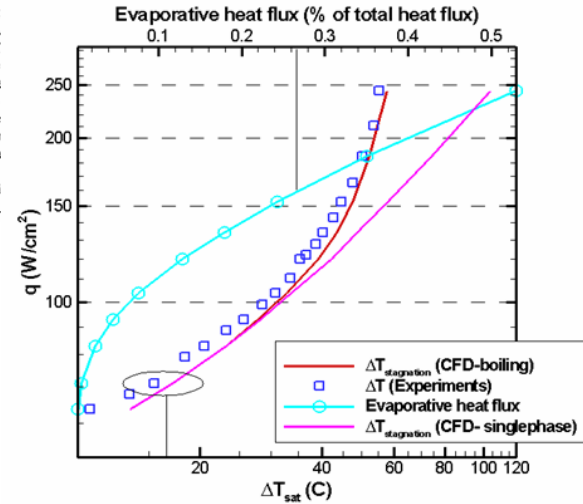
<sup>a</sup> National Renewable Energy Laboratory, MS 1633, 1617 Cole Boulevard Golden, CO 80401-3393, USA  
<sup>b</sup> ANSYS Inc., Fluid Business Unit, 10 Cavendish Court, Centerra Park Resource, Lebanon, NH 03766, USA

Received 25 October 2006; received in revised form 21 May 2007

### Abstract

Boiling jet used for DC-off switches. T problem quite In this paper the CFD code jets (submerge use R134a as © 2007 Elsevi

Keywords: Boili



brid vehicles, inverters are Ts), which are used as on/ s the thermal management k for these computations is for boiling water and R113 F package simulations that

# Accomplishments to Date (for projects funded in prior FYs)

## Two-phase Jet and Spray Cooling tests

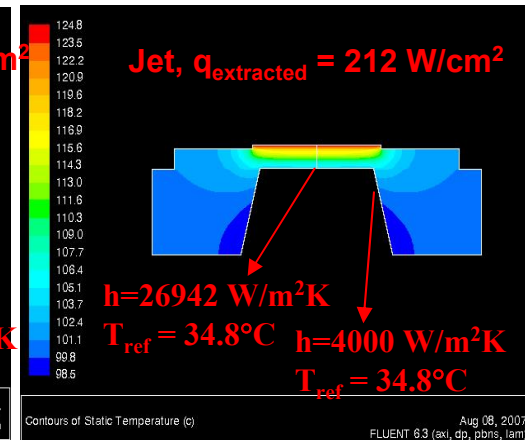
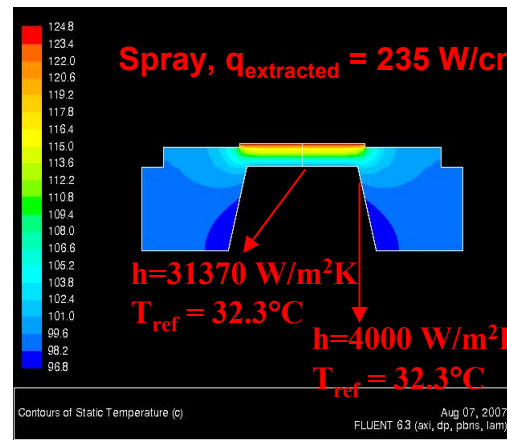
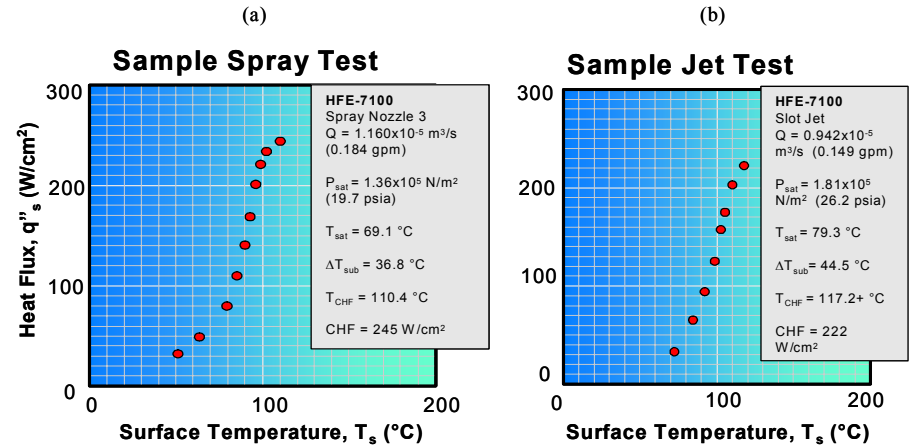


### Status

- Mudawar Thermal Systems has constructed the test apparatus for two-phase jet and spray cooling
- Nucleate boiling curves have been established for HFE-7100 using jets and sprays on a 1x1 cm test surface
- Demonstrated conditions with two-phase dielectric coolant that could achieve  $> 200 \text{ W/cm}^2$  heat flux while maintaining  $125^\circ \text{C}$  chip temperature

### Benefits

- Two-phase heat transfer provides an alternative means for achieving high heat flux requirements





# Project Objectives for FY08

- **Complete characterization of single and two-phase spray and jets**
  - Perform thermal testing and also validation of thermal models for low thermal resistance IGBT structure design
  - Publish consistent, objective comparison of existing technologies
- **Assess the potential with spray and jet technologies to meet thermal targets using 105°C coolant**
- **Identify additional thermal control parameters to enable system cost, weight, and volume reduction**
  - Surface area enhancement
  - Materials to improve thermal performance, cost and weight
  - Overall system cost reduction
- **Develop optimized/integrated thermal solution**
  - Thermal control integrated with PE system
  - Close collaboration with ORNL and industry partners

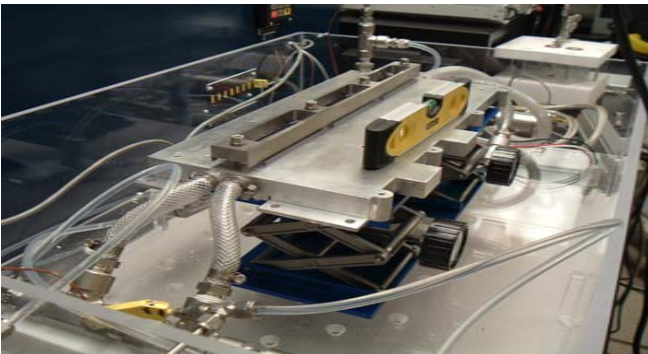
# Technical Approach for FY08



Publish a paper on self-oscillating jets at Semitherm, 3/08



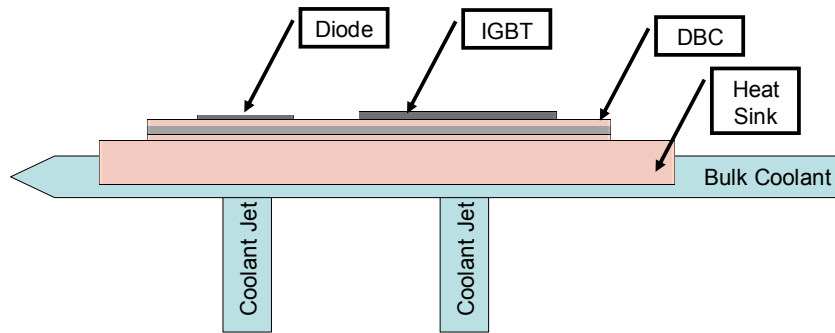
Publish a paper on Two-Phase Experimental and Model Validation at ITHERM, 5/08



Complete Thermal testing/validation and submit a conference paper, 9/08

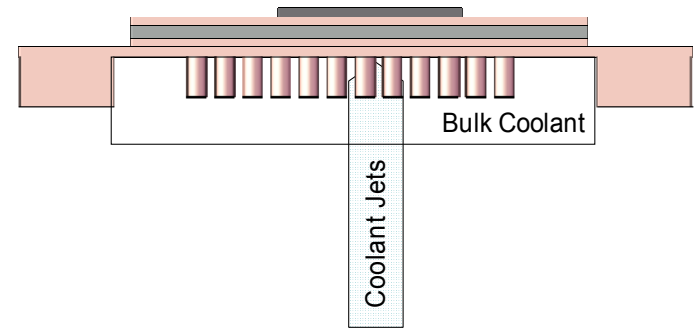
# Technical Approach for FY08

## 1. Maximizing Heat Transfer Coefficient, $h$



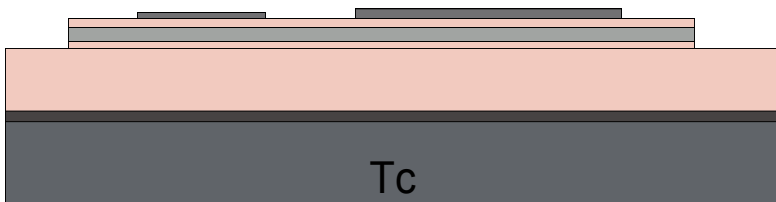
Assessing existing technologies like spray, oscillating jets, direct back side cooling, etc.

## 2. Enhancing Surface Area, $A$



Surface area is a key parameter for enhancing heat transfer, enabling volume and cost reduction

## 3. Optimizing Cold Plate Temperature, $T_B$

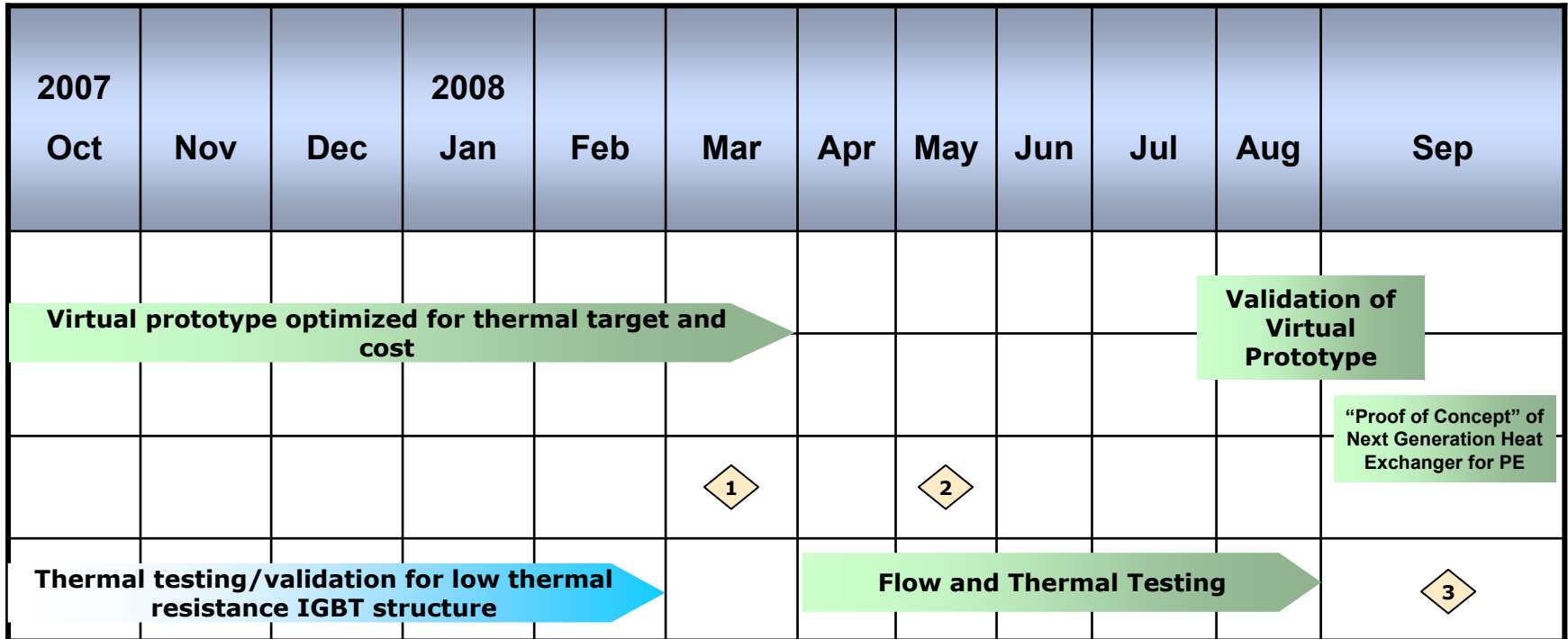


Alternate materials would be explored from the die to the cold plate for cost reduction

## 4. Concurrent Engineering

Close collaboration with ORNL PE Tech team and industry partners to drive cost reduction

# Timeline



- **Publish**

- 1 Self-oscillating jet paper (Semitherm, co-authored with Bowles Fluidics), 3/08
- 2 Two-phase experiments with numerical results (ITherm, co-authored with Mudawar Thermal Systems), 5/08
- 3 Submit a conference paper on Low Thermal Resistance IGBT Structure (9/08)

# **The Challenges/Barriers to implement 105°C coolant**

- **Extra cost due to design changes could exceed the cost benefits due to the elimination of a separate coolant loop.**
- **Size of the capacitors could increase.**
- **Long term reliability could decrease for PE, motors and capacitors.**
- **Flux strength of the motors could decrease by about 20 – 30% when the coolant at 105° C is used.**
- **Stator losses could increase by about 30% causing the breakdown of winding insulation.**

# Beyond FY08

## FY09

- **Work with ORNL and industry partners to implement low cost 105°C thermal solution**
- **Interaction with reliability efforts**
  - **Provide thermal performance data and design parameters to reliability models**

# Questions

